



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PACKAGE CODE 5368 IS TO ACCOUNT FOR PGE AND THE BUILT-IN HEAT SPREADER.

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TITLE: 516 THERMALLY ENHANCED PBGA, WITH HEAT SPREADER, 27 x 27 PKG, 1MM PITCH	DOCUMENT NO: 98ASA10789D	REV: A
	STANDARD: JEDEC MS-034	
	SOT1665-1	14 MAR 2016